

Hall IC Series

Omnipolar Detection Hall ICs (Polarity detection for both S and N features dual outputs)


BU52004GUL, BU52014HFV

No.10045EDT01

●Description

The BU52004GUL and BU52014HFV are bipolar Hall ICs incorporating a polarity determination circuit that enables operation (output) on both the S- and N-poles, with the polarity judgment based on the output processing configuration. These Hall IC products can be in with movie, mobile phone and other applications involving crystal panels to detect the (front-back) location or determine the rotational direction of the panel.

●Features

- 1) Omnipolar detection (polarity detection for both S and N features dual outputs)
- 2) Micropower operation (small current using intermittent operation method)
- 3) Ultra-compact CSP4 package(BU52004GUL)
- 4) Small outline package (BU52014HFV)
- 5) Line up of supply voltage
 - For 1.8V Power supply voltage (BU52014HFV)
 - For 3.0V Power supply voltage (BU52004GUL)
- 6) Polarity judgment and output on both poles (OUT1: S-pole output; OUT2: N-pole output)
- 7) High ESD resistance 8kV(HBM)

●Applications

Mobile phones, notebook computers, digital video camera, digital still camera, etc.

●Product Lineup

Product name	Supply voltage (V)	Operate point (mT)	Hysteresis (mT)	Period (ms)	Supply current (AVG.) (μA)	Output type	Package
BU52004GUL	2.40~3.30	+/-3.7 ※	0.8	50	8.0	CMOS	VCSP50L1
BU52014HFV	1.65~3.30	+/-3.0 ※	0.9	50	5.0	CMOS	HVSOF5

※Plus is expressed on the S-pole; minus on the N-pole

●Absolute Maximum Ratings

BU52004GUL (Ta=25°C)

PARAMETERS	SYMBOL	LIMIT	UNIT
Power Supply Voltage	VDD	-0.1 ~ +4.5 ^{※1}	V
Output Current	IOUT	±1	mA
Power Dissipation	Pd	420 ^{※2}	mW
Operating Temperature Range	Topr	-40 ~ +85	°C
Storage Temperature Range	Tstg	-40 ~ +125	°C

※1. Not to exceed Pd

※2. Reduced by 4.20mW for each increase in Ta of 1°C over 25°C (mounted on 50mm × 58mm Glass-epoxy PCB)

BU52014 HFV (Ta=25°C)

PARAMETERS	SYMBOL	LIMIT	UNIT
Power Supply Voltage	VDD	-0.1 ~ +4.5 ^{※3}	V
Output Current	IOUT	±0.5	mA
Power Dissipation	Pd	536 ^{※4}	mW
Operating Temperature Range	Topr	-40 ~ +85	°C
Storage Temperature Range	Tstg	-40 ~ +125	°C

※3. Not to exceed Pd

※4. Reduced by 5.36mW for each increase in Ta of 1°C over 25°C (mounted on 70mm × 70mm × 1.6mm Glass-epoxy PCB)

●Magnetic, Electrical Characteristics

BU52004GUL (Unless otherwise specified, V_{DD}=3.0V, Ta=25°C)

PARAMETERS	SYMBOL	LIMIT			UNIT	CONDITIONS
		MIN	TYP	MAX		
Power Supply Voltage	V _{DD}	2.4	3.0	3.3	V	
Operate Point	B _{opS}	-	3.7	5.5	mT	OUTPUT : OUT1 (respond the south pole)
	B _{opN}	-5.5	-3.7	-		OUTPUT : OUT2 (respond the north pole)
Release Point	B _{rpS}	0.8	2.9	-	mT	OUTPUT : OUT1 (respond the south pole)
	B _{rpN}	-	-2.9	-0.8		OUTPUT : OUT2 (respond the north pole)
Hysteresis	B _{hysS}	-	0.8	-	mT	
	B _{hysN}	-	0.8	-		
Period	T _p	-	50	100	ms	
Output High Voltage	V _{OH}	V _{DD} -0.4	-	-	V	B _{rpN} <B<B _{rpS} ※5 I _{OUT} =-1.0mA
Output Low Voltage	V _{OL}	-	-	0.4	V	B<B _{opN} , B _{opS} <B ※5 I _{OUT} =+1.0mA
Supply Current	I _{DD(AVG)}	-	8	12	μA	Average
Supply Current During Startup Time	I _{DD(EN)}	-	4.7	-	mA	During Startup Time Value
Supply Current During Standby Time	I _{DD(DIS)}	-	3.8	-	μA	During Standby Time Value

※5. B = Magnetic flux density

1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period (T_p) to become definite output.

Radiation hardness is not designed.

BU52014HFV (Unless otherwise specified, V_{DD}=1.80V, Ta=25°C)

PARAMETERS	SYMBOL	LIMIT			UNIT	CONDITIONS
		MIN	TYP	MAX		
Power Supply Voltage	V _{DD}	1.65	1.80	3.30	V	
Operate Point	B _{opS}	-	3.0	5.0	mT	OUTPUT : OUT1 (respond the south pole)
	B _{opN}	-5.0	-3.0	-		OUTPUT : OUT2 (respond the north pole)
Release Point	B _{rpS}	0.6	2.1	-	mT	OUTPUT : OUT1 (respond the south pole)
	B _{rpN}	-	-2.1	-0.6		OUTPUT : OUT2 (respond the north pole)
Hysteresis	B _{hysS}	-	0.9	-	mT	
	B _{hysN}	-	0.9	-		
Period	T _p	-	50	100	ms	
Output High Voltage	V _{OH}	V _{DD} -0.2	-	-	V	B _{rpN} <B<B _{rpS} ※6 I _{OUT} =-0.5mA
Output Low Voltage	V _{OL}	-	-	0.2	V	B<B _{opN} , B _{opS} <B ※6 I _{OUT} =+0.5mA
Supply Current 1	I _{DD1(AVG)}	-	5	8	μA	V _{DD} =1.8V, Average
Supply Current During Startup Time 1	I _{DD1(EN)}	-	2.8	-	mA	V _{DD} =1.8V, During Startup Time Value
Supply Current During Standby Time 1	I _{DD1(DIS)}	-	1.8	-	μA	V _{DD} =1.8V, During Standby Time Value
Supply Current 2	I _{DD2(AVG)}	-	8	12	μA	V _{DD} =2.7V, Average
Supply Current During Startup Time 2	I _{DD2(EN)}	-	4.5	-	mA	V _{DD} =2.7V, During Startup Time Value
Supply Current During Standby Time 2	I _{DD2(DIS)}	-	4.0	-	μA	V _{DD} =2.7V, During Standby Time Value

※6. B = Magnetic flux density

1mT=10Gauss

Positive (“+”) polarity flux is defined as the magnetic flux from south pole which is direct toward to the branded face of the sensor.

After applying power supply, it takes one cycle of period (T_p) to become definite output.

Radiation hardness is not designed.

●Figure of measurement circuit

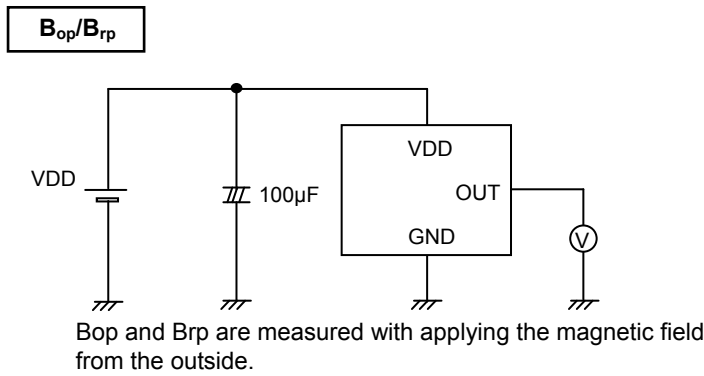


Fig.1 B_{op},B_{rp} measurement circuit

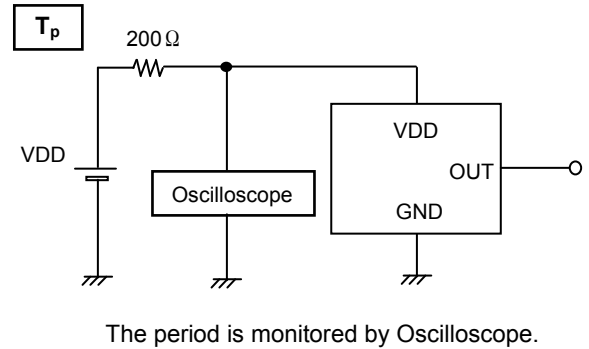
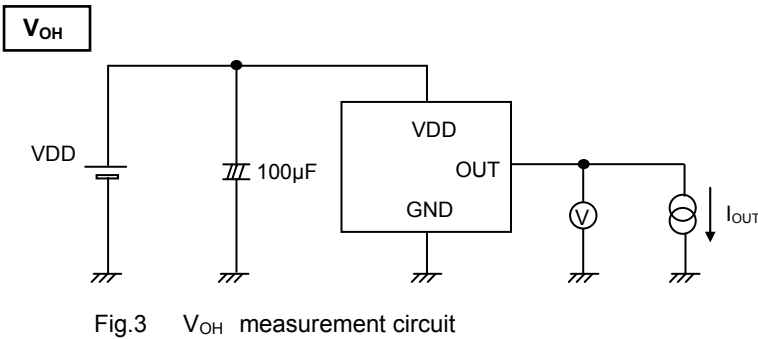
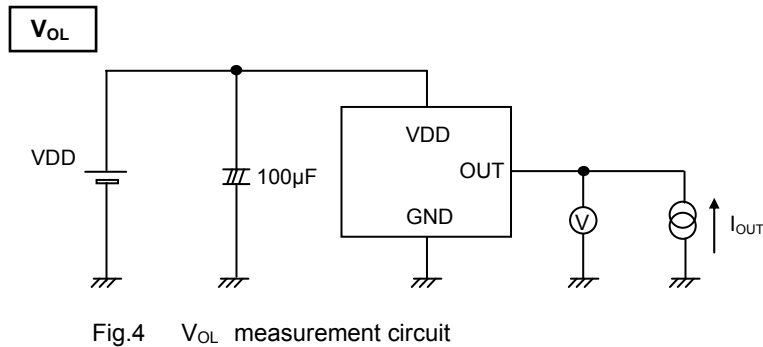


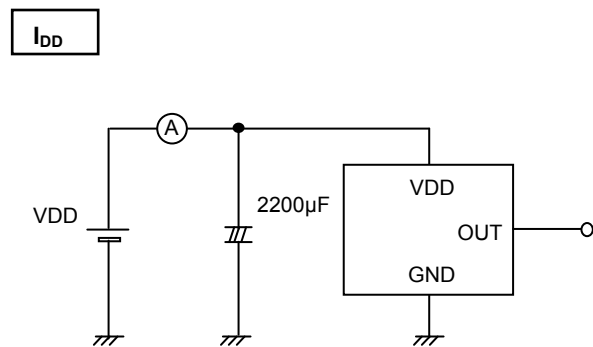
Fig.2 T_p measurement circuit



Product Name	I _{OUT}
BU52004GUL	1.0mA
BU52014HFV	0.5mA



Product Name	I _{OUT}
BU52004GUL	1.0mA
BU52014HFV	0.5mA



● Technical (Reference) Data
 BU52004GUL (V_{DD}=2.4V~3.3V type)

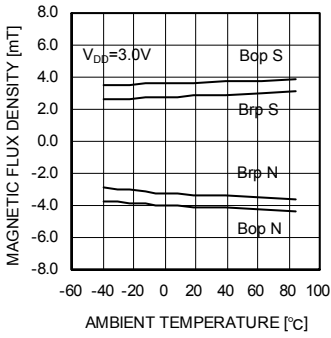


Fig.6 Bop,Brp – Ambient temperature

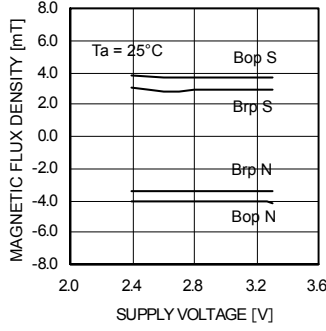


Fig.7 Bop,Brp – Supply voltage

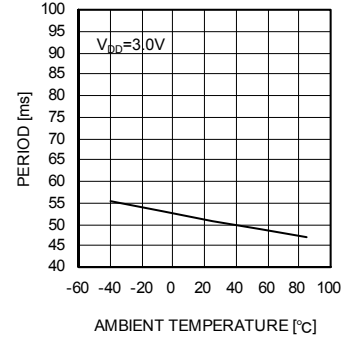


Fig.8 T_P– Ambient temperature

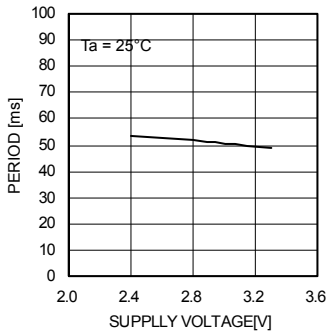


Fig.9 T_P – Supply voltage

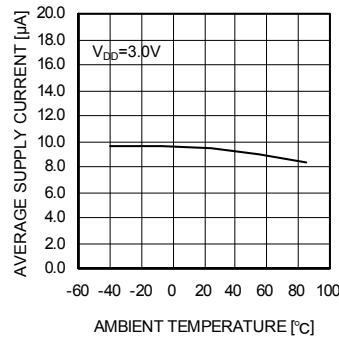


Fig.10 I_{DD} – Ambient temperature

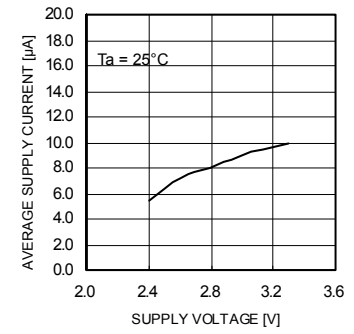


Fig.11 I_{DD} – Supply voltage

BU52014HFV (V_{DD}=1.65V~3.3V type)

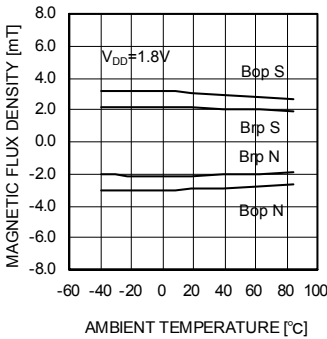


Fig.12 Bop,Brp – Ambient temperature

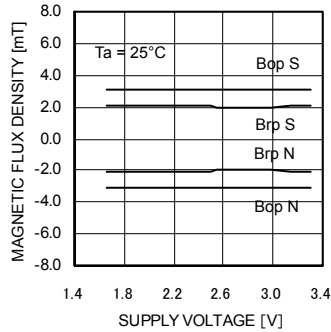


Fig.13 Bop,Brp – Supply voltage

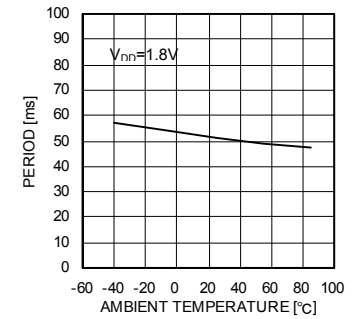


Fig.14 T_P– Ambient temperature

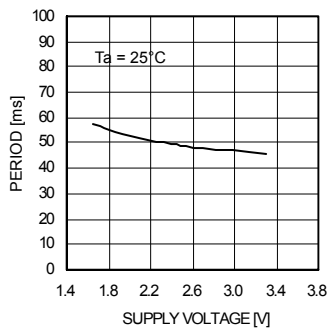


Fig.15 T_P– Supply voltage

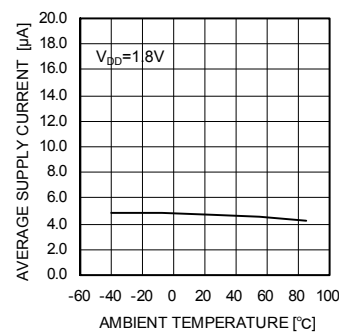


Fig.16 I_{DD} – Ambient temperature

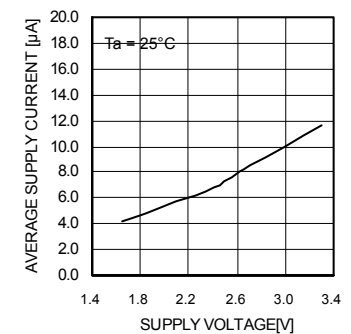


Fig.17 I_{DD} – Supply voltage

●Block Diagram
BU52004GUL

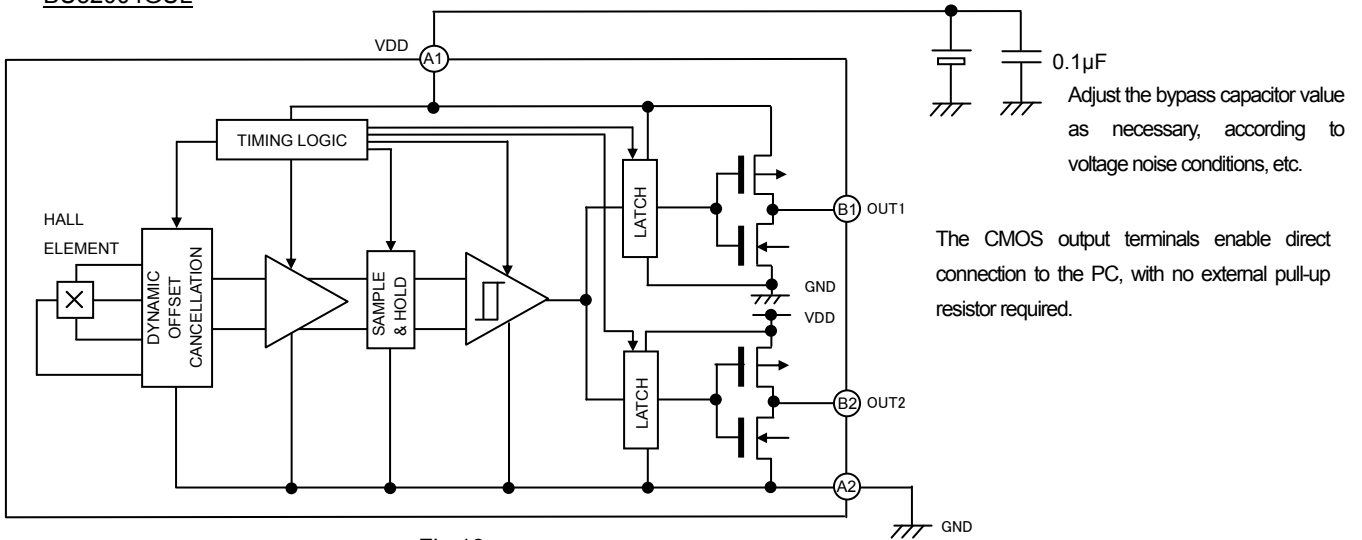
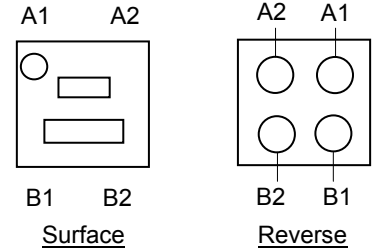


Fig.18

PIN No.	PIN NAME	FUNCTION	COMMENT
A1	VDD	POWER SUPPLY	
A2	GND	GROUND	
B1	OUT1	OUTPUT(respond the south pole)	
B2	OUT2	OUTPUT(respond the north pole)	



BU52014HFV

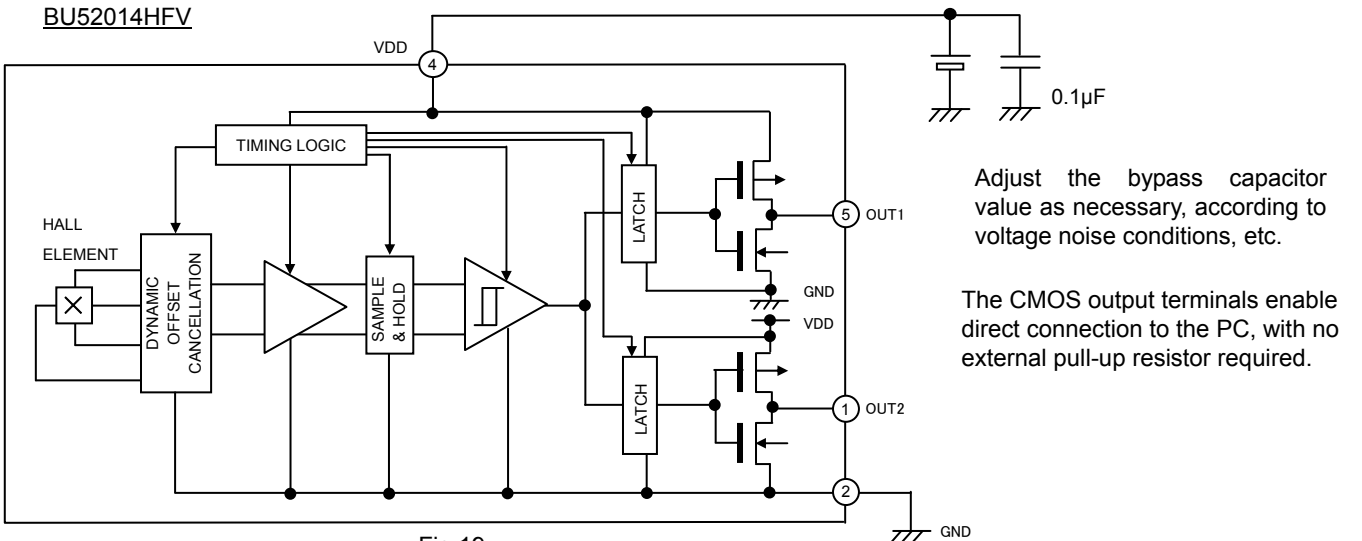
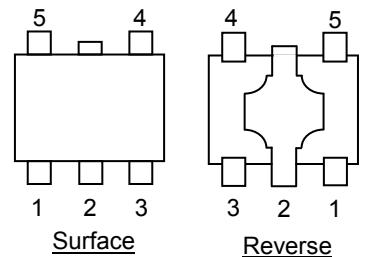


Fig.19

PIN No.	PIN NAME	FUNCTION	COMMENT
1	OUT2	OUTPUT (respond the north pole)	
2	GND	GROUND	
3	N.C.		OPEN or Short to GND.
4	VDD	POWER SUPPLY	
5	OUT1	OUTPUT (respond the south pole)	



● Description of Operations

Micropower Operation (Small current using intermittent action)

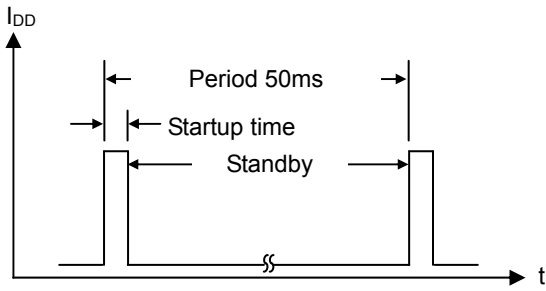


Fig.20

The dual output bipolar detection Hall IC adopts an intermittent operation method to save energy. At startup, the Hall elements, amp, comparator and other detection circuits power ON and magnetic detection begins. During standby, the detection circuits power OFF, thereby reducing current consumption. The detection results are held while standby is active, and then output.

Reference period: 50ms (MAX100ms)
Reference startup time: 48 μ s

(Offset Cancellation)

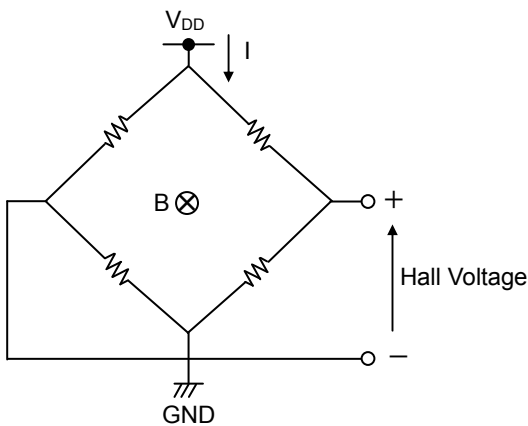


Fig.21

The Hall elements form an equivalent Wheatstone (resistor) bridge circuit. Offset voltage may be generated by a differential in this bridge resistance, or can arise from changes in resistance due to package or bonding stress. A dynamic offset cancellation circuit is employed to cancel this offset voltage.

When Hall elements are connected as shown in Fig. 21 and a magnetic field is applied perpendicular to the Hall elements, voltage is generated at the mid-point terminal of the bridge. This is known as Hall voltage.

Dynamic cancellation switches the wiring (shown in the figure) to redirect the current flow to a 90° angle from its original path, and thereby cancels the Hall voltage.

The magnetic signal (only) is maintained in the sample/hold circuit during the offset cancellation process and then released.

(Magnetic Field Detection Mechanism)

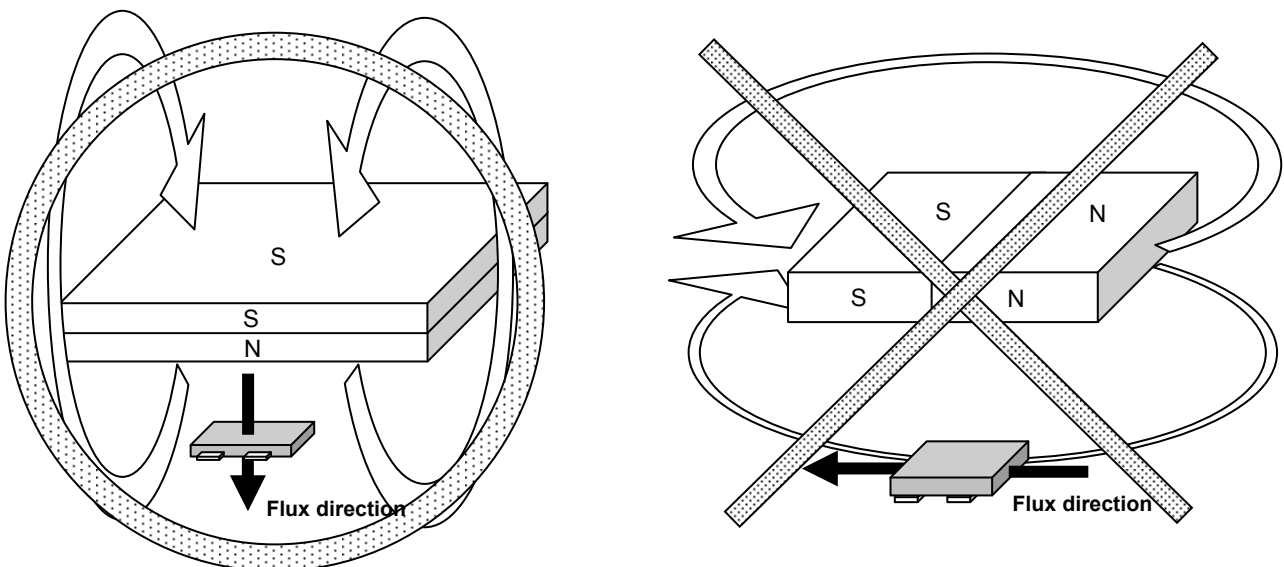


Fig.22

The Hall IC cannot detect magnetic fields that run horizontal to the package top layer. Be certain to configure the Hall IC so that the magnetic field is perpendicular to the top layer.

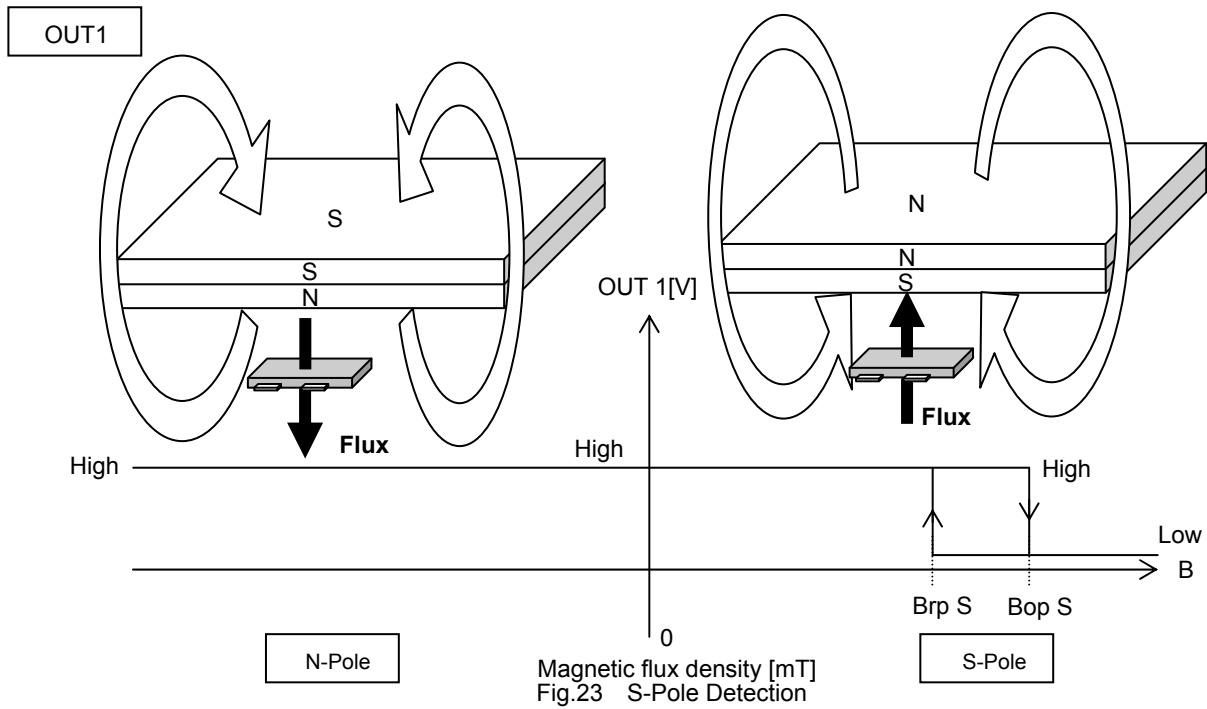


Fig.23 S-Pole Detection

The OUT1 pin detects and outputs for the S-pole only. Since it is unipolar, it does not recognize the N-pole.

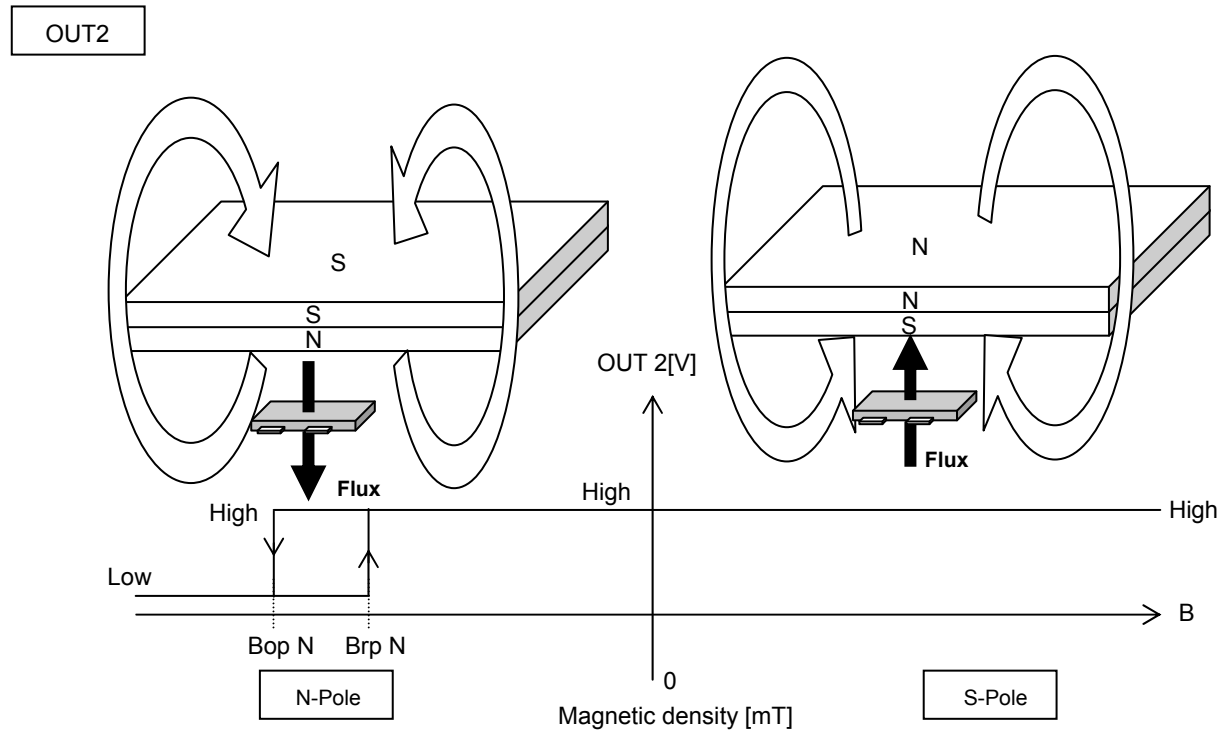


Fig.24 N-Pole Detection

The OUT2 pin detects and outputs for the N-pole only. Since it is unipolar, it does not recognize the S-pole. The dual output Omnipolar detection Hall IC detects magnetic fields running perpendicular to the top surface of the package. There is an inverse relationship between magnetic flux density and the distance separating the magnet and the Hall IC: when distance increases magnetic density falls. When it drops below the operate point (Bop), output goes HIGH. When the magnet gets closer to the IC and magnetic density rises, to the operate point, the output switches LOW. In LOW output mode, the distance from the magnet to the IC increases again until the magnetic density falls to a point just below Bop, and output returns HIGH. (This point, where magnetic flux density restores HIGH output, is known as the release point, Brp.) This detection and adjustment mechanism is designed to prevent noise, oscillation and other erratic system operation.

● Intermittent Operation at Power ON

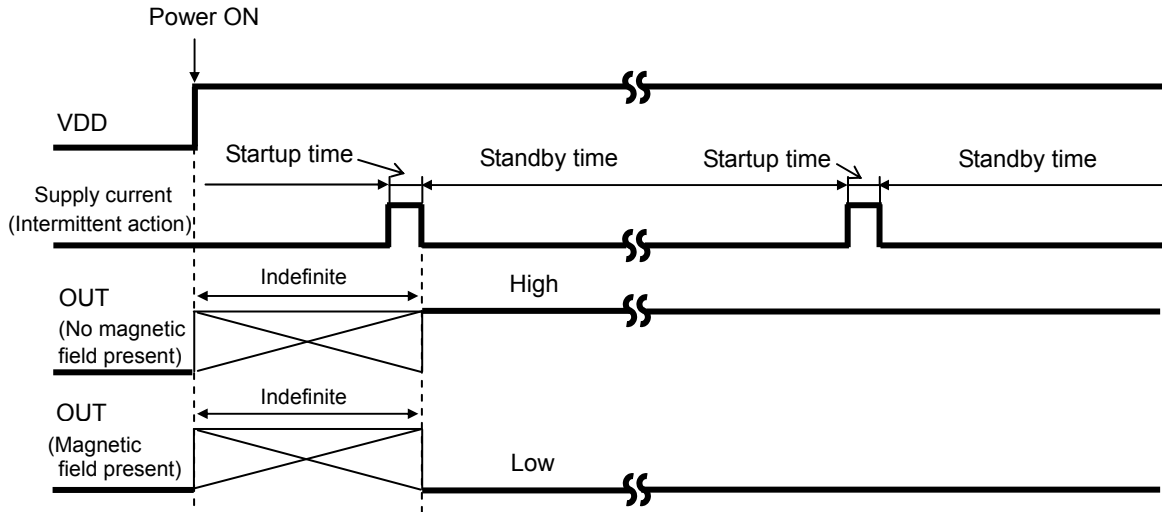


Fig.25

The dual output Omnipolar detection Hall IC adopts an intermittent operation method in detecting the magnetic field during startup, as shown in Fig. 25. It outputs to the appropriate terminal based on the detection result and maintains the output condition during the standby period. The time from power ON until the end of the initial startup period is an indefinite interval, but it cannot exceed the maximum period, 100ms. To accommodate the system design, the Hall IC output read should be programmed within 100ms of power ON, but after the time allowed for the period ambient temperature and supply voltage.

● Magnet Selection

Of the two representative varieties of permanent magnet, neodymium generally offers greater magnetic power per volume than ferrite, thereby enabling the highest degree of miniaturization. Thus, neodymium is best suited for small equipment applications. Fig. 26 shows the relation between the size (volume) of a neodymium magnet and magnetic flux density. The graph plots the correlation between the distance (L) from three versions of a 4mm X 4mm cross-section neodymium magnet (1mm, 2mm, and 3mm thick) and magnetic flux density. Fig. 27 shows Hall IC detection distance – a good guide for determining the proper size and detection distance of the magnet. Based on the BU52014HFV operating point max 5.0 mT, the minimum detection distance for the 1mm, 2mm and 3mm magnets would be 7.6mm, 9.2mm, and 10.4mm, respectively. To increase the magnet's detection distance, either increase its thickness or sectional area.

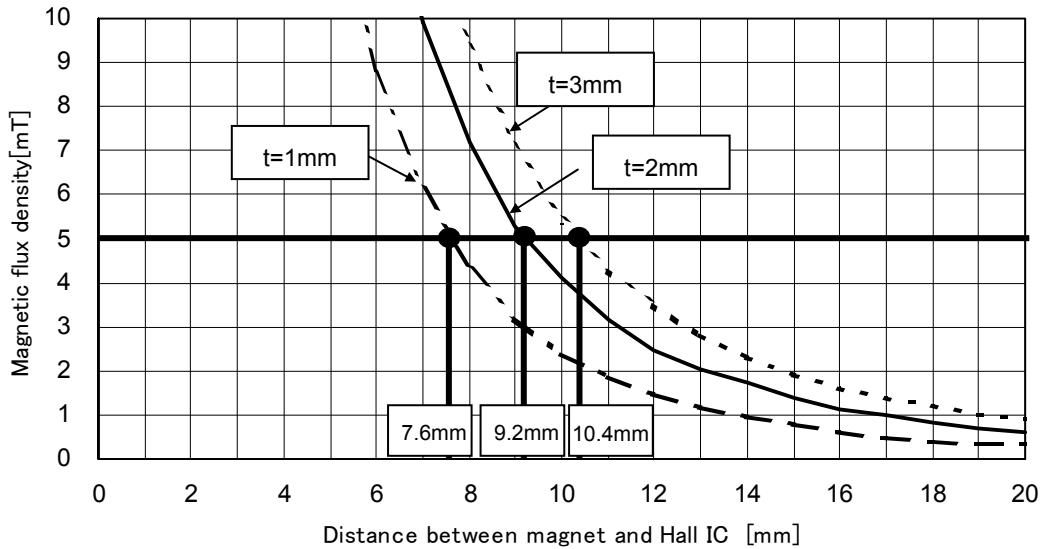


Fig.26

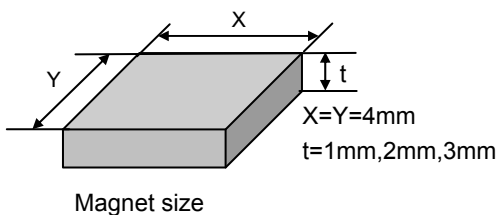
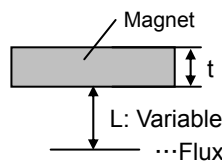


Fig.27 Magnet Dimensions and Flux Density Measuring Point



Magnet material: NEOMAX-44H (material)
 Maker: NEOMAX CO.,LTD.



...Flux density measuring point

● Operation Notes

1) Absolute maximum ratings

Exceeding the absolute maximum ratings for supply voltage, operating conditions, etc. may result in damage to or destruction of the IC. Because the source (short mode or open mode) cannot be identified if the device is damaged in this way, it is important to take physical safety measures such as fusing when implementing any special mode that operates in excess of absolute rating limits.

2) GND voltage

Make sure that the GND terminal potential is maintained at the minimum in any operating state, and is always kept lower than the potential of all other pins.

3) Thermal design

Use a thermal design that allows for sufficient margin in light of the power dissipation (P_d) in actual operating conditions.

4) Pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. Mounting errors, such as improper positioning or orientation, may damage or destroy the device. The IC may also be damaged or destroyed if output pins are shorted together, or if shorts occur between the output pin and supply pin or GND.

5) Positioning components in proximity to the Hall IC and magnet

Positioning magnetic components in close proximity to the Hall IC or magnet may alter the magnetic field, and therefore the magnetic detection operation. Thus, placing magnetic components near the Hall IC and magnet should be avoided in the design if possible. However, where there is no alternative to employing such a design, be sure to thoroughly test and evaluate performance with the magnetic component(s) in place to verify normal operation before implementing the design.

6) Slide-by position sensing

Fig.29 depicts the slide-by configuration employed for position sensing. Note that when the gap (d) between the magnet and the Hall IC is narrowed, the reverse magnetic field generated by the magnet can cause the IC to malfunction. As seen in Fig.30, the magnetic field runs in opposite directions at Point A and Point B. Since the dual output Omnipolar detection Hall IC can detect the S-pole at Point A and the N-pole at Point B, it can wind up switching output ON as the magnet slides by in the process of position detection. Fig. 31 plots magnetic flux density during the magnet slide-by. Although a reverse magnetic field was generated in the process, the magnetic flux density decreased compared with the center of the magnet. This demonstrates that slightly widening the gap (d) between the magnet and Hall IC reduces the reverse magnetic field and prevents malfunctions.

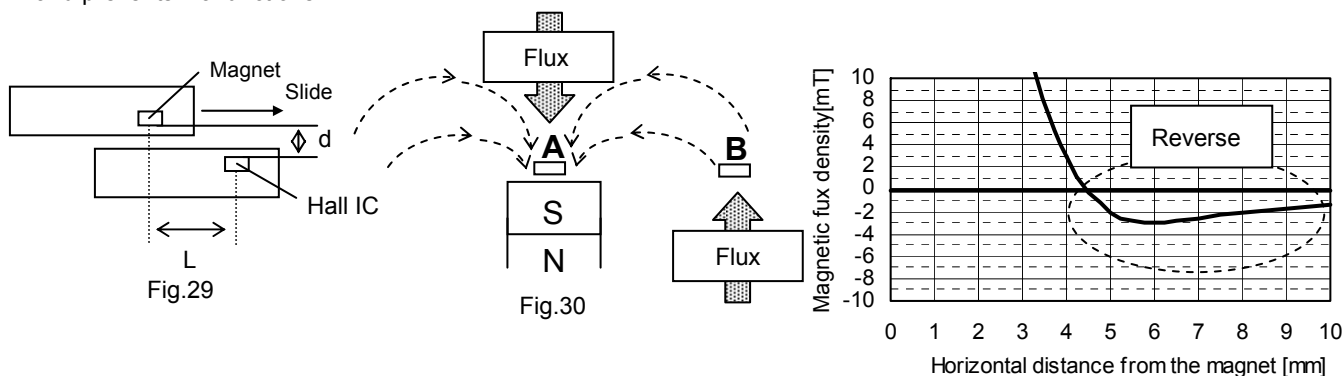


Fig.31

7) Operation in strong electromagnetic fields

Exercise extreme caution about using the device in the presence of a strong electromagnetic field, as such use may cause the IC to malfunction.

8) Common impedance

Make sure that the power supply and GND wiring limits common impedance to the extent possible by, for example, employing short, thick supply and ground lines. Also, take measures to minimize ripple such as using an inductor or capacitor.

9) GND wiring pattern

When both a small-signal GND and high-current GND are provided, single-point grounding at the reference point of the set PCB is recommended, in order to separate the small-signal and high-current patterns, and to ensure that voltage changes due to the wiring resistance and high current do not cause any voltage fluctuation in the small-signal GND. In the same way, care must also be taken to avoid wiring pattern fluctuations in the GND wiring pattern of external components.

10) Exposure to strong light

Exposure to halogen lamps, UV and other strong light sources may cause the IC to malfunction. If the IC is subject to such exposure, provide a shield or take other measures to protect it from the light. In testing, exposure to white LED and fluorescent light sources was shown to have no significant effect on the IC.

11) Power source design

Since the IC performs intermittent operation, it has peak current when it's ON. Please taking that into account and under examine adequate evaluations when designing the power source.

Notice

Precaution on using ROHM Products

- Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - Installation of protection circuits or other protective devices to improve system safety
 - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
 - Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
 - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

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General Precaution

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